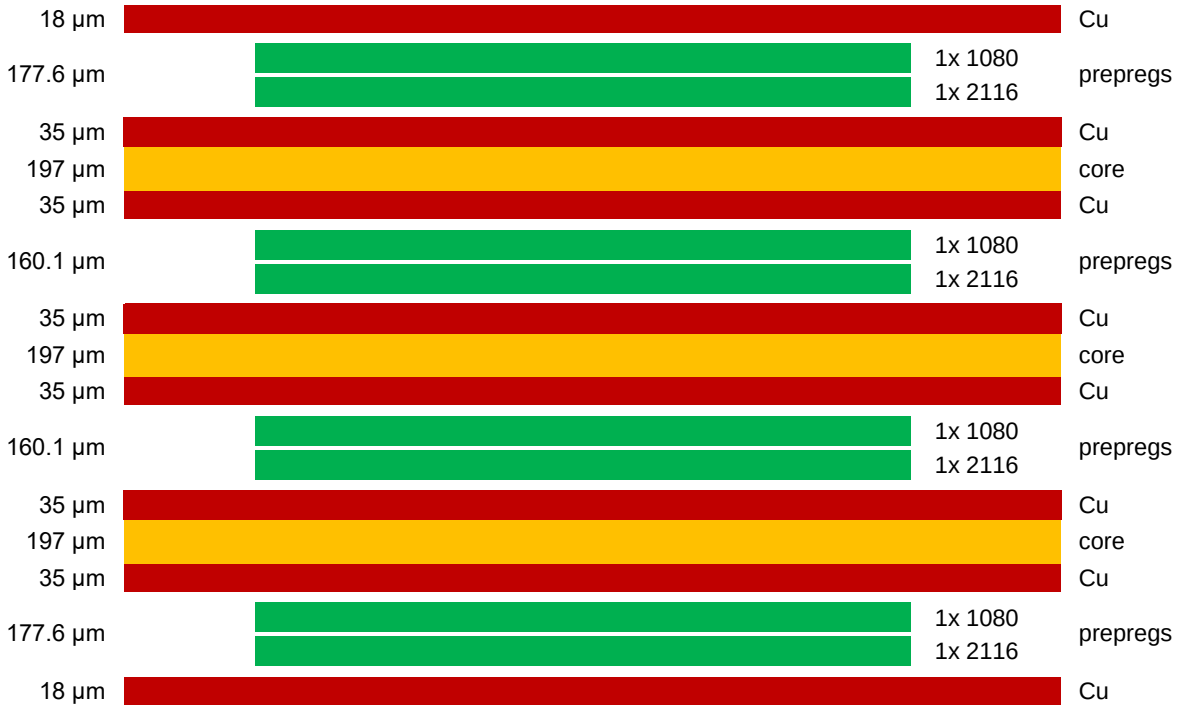
8-layer PCB stackup



Parameters

material type:	Standard FR4 TG130
base materials thickness (after lamination):	1.512 mm
final PCB thickness:	1.68 mm ±0.15 mm
Cu thickness:	
outer layers (base thickness, without plating):	18 µm
inner layers (final thickness):	35 µm / 35 µm / 35 µm / 35 µm / 35 µm / 35 µm